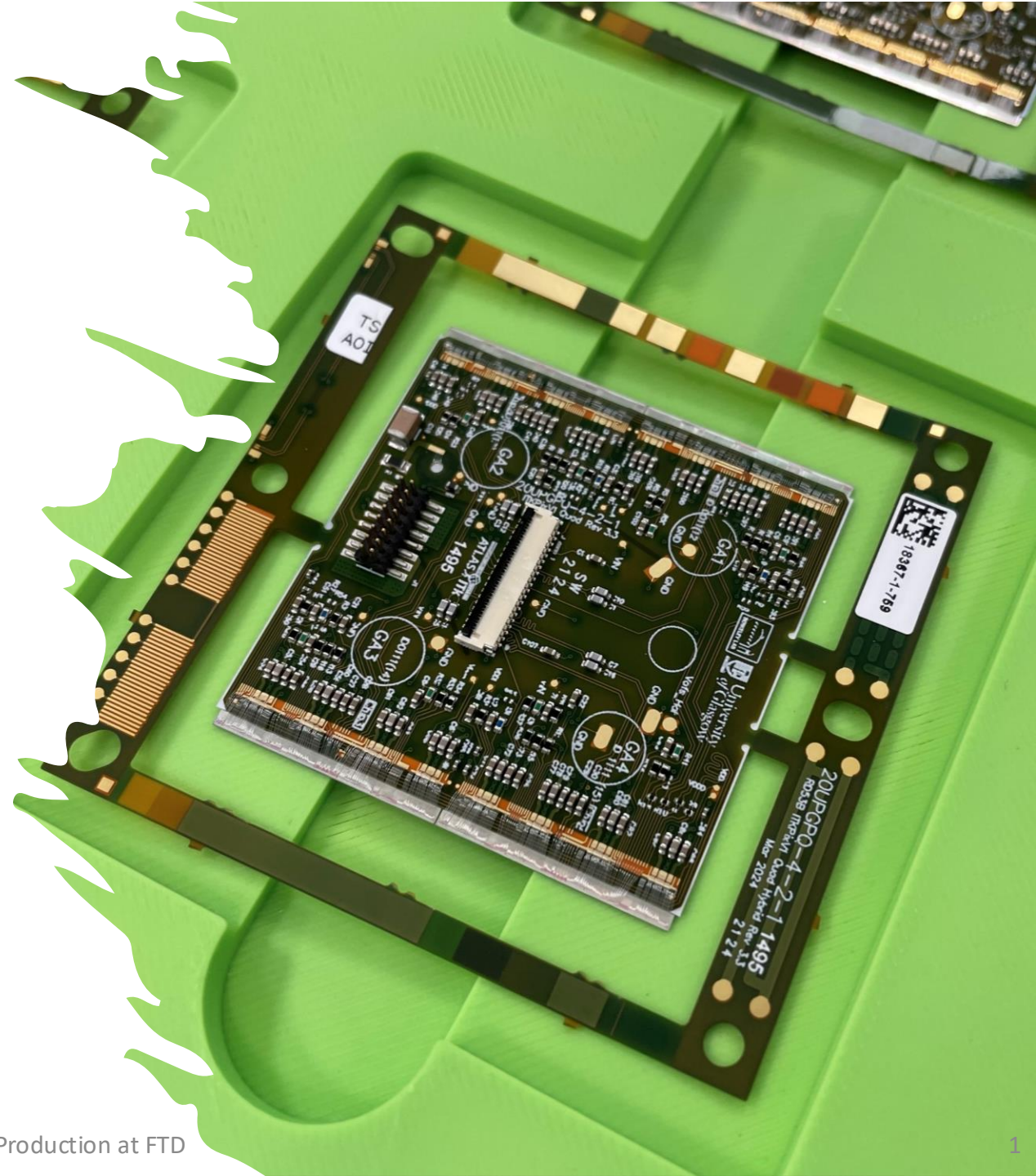


ATLAS ITk Module Production - at FTD



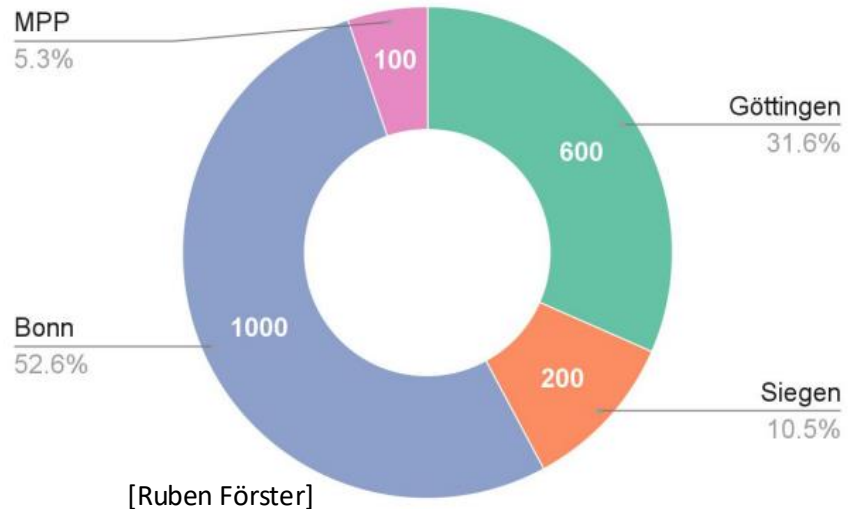
News from testing setup commissioning

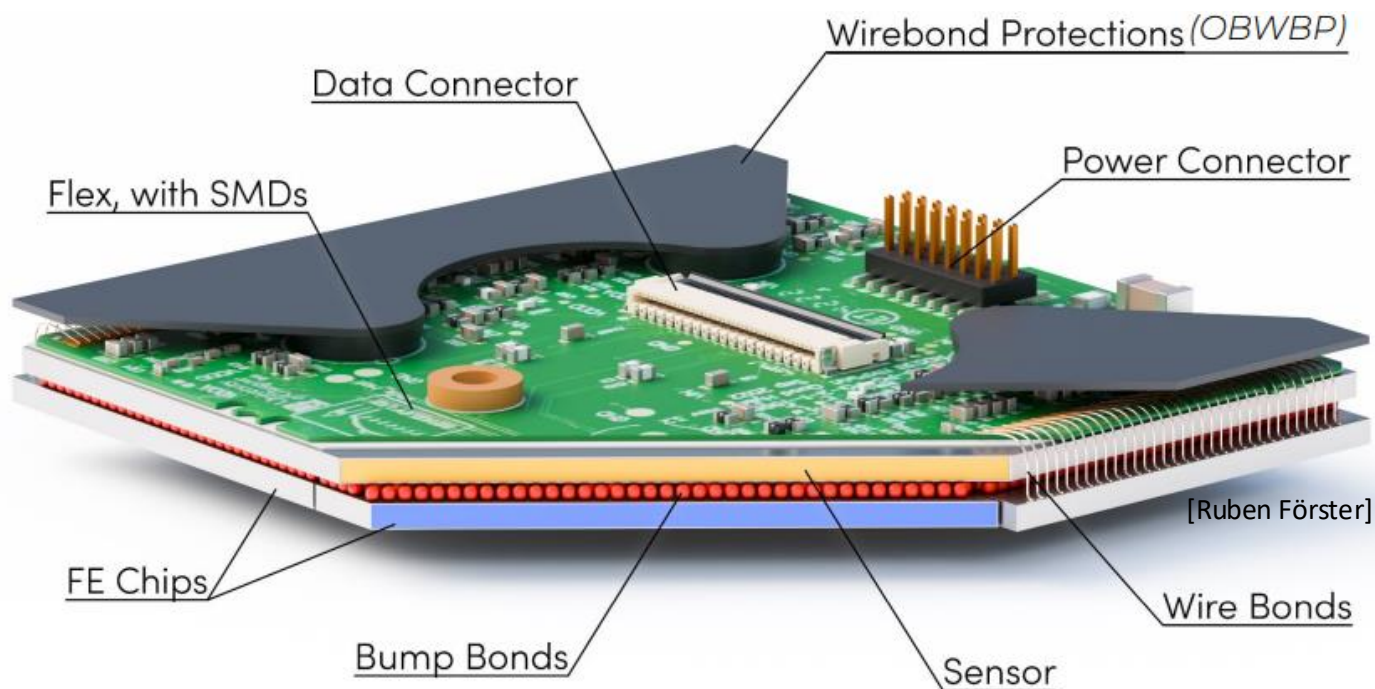
- Two test stands in cleanroom to cope with ATLAS module testing rate
- ISO7: Hardware connected -> need to discuss network things with IT
- ISO6: setup in "preparation"
 - Setup will be placed on tables in ISO6
 - Jerome will install tubing into ISO6 to connect to dry pressured air (OK for us if this will be done until mid/end of August)
 - Need to clean and move things over to ISO6 -> will only happen as soon as ISO7 setup is running
 - Radiation safety acceptance test needs to be done by Fabian



BACKUP

- In total, ~11 000 modules must be built (~8000 on-detector modules)
- World-wide effort amongst many different institutes
- Germany contributes to production with ~1900 modules
 - Munich: 100 modules
 - Siegen: 200 modules
 - Göttingen: 600 modules
 - **Bonn: 1000 modules (+600 assemblies from Göttingen)**



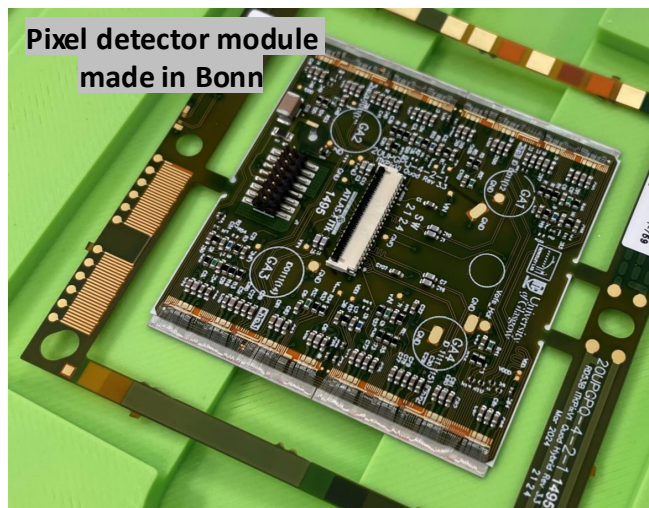


- Main components of hybrid pixel module:
 - Flexible PCB
 - Silicon sensor
 - Silicon readout chip
- A few facts
 - Module size: $4 \times 4 \text{ cm}^2$
 - Module thickness: $600 - 700 \text{ um}$
 - 4 R/O chips on a single sensor tile
 - 400×384 pixels on each R/O chip
 - Each pixel has a size of $50 \times 50 \text{ um}^2$
 - Very fast and radiation tolerant R/O chip
- To be used in the new ATLAS pixel detector
- Smallest unit of the detector

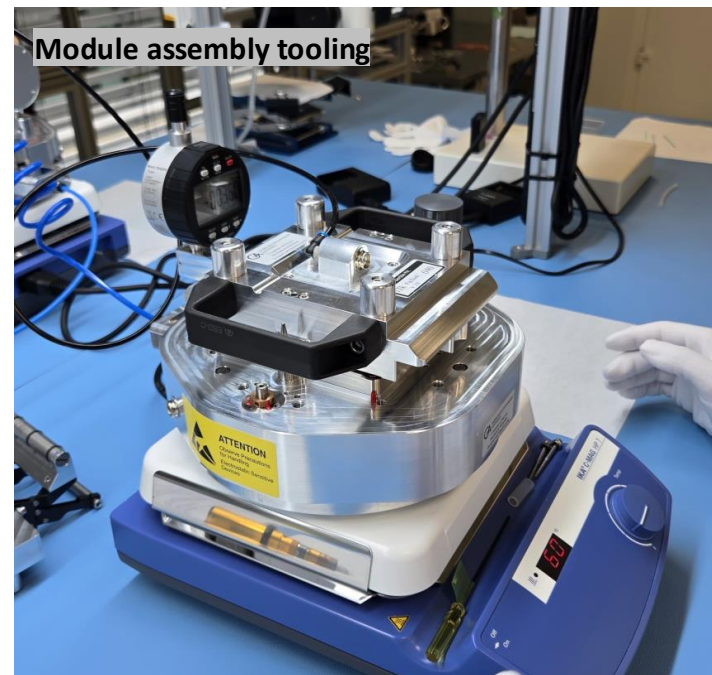
- Module production consists of many different production steps
- Extensive QC measurements after each production step are required to ensure good quality along the full chain of production
- Most of the production steps happen in the ISO7 clean room area
- So far, 450/1600 modules are assembled (flex-attach)
- Team effort: many technicians, working students, staff and PhD students...
 - more than 14 people are actively working on the module production in the clean room



Part of the whole team
(not a one-man-show)

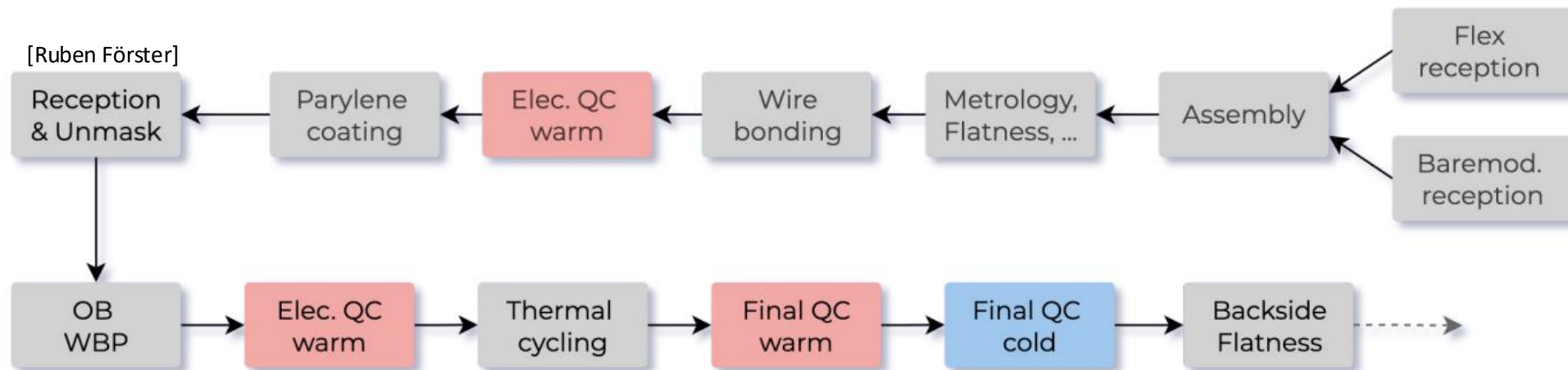


Pixel detector module
made in Bonn



Module assembly tooling

- ... Reception of flex and bare module
- ... Glue flex to bare module -> mechanical connection
- ... Wirebonding of module -> electrical connection
- ... Parylene masking/demasking -> parylene coating for HV protection
- ... Canopy attachment (OBWBP) -> protect wirebonds
- Many QC steps and electrical testing in between steps

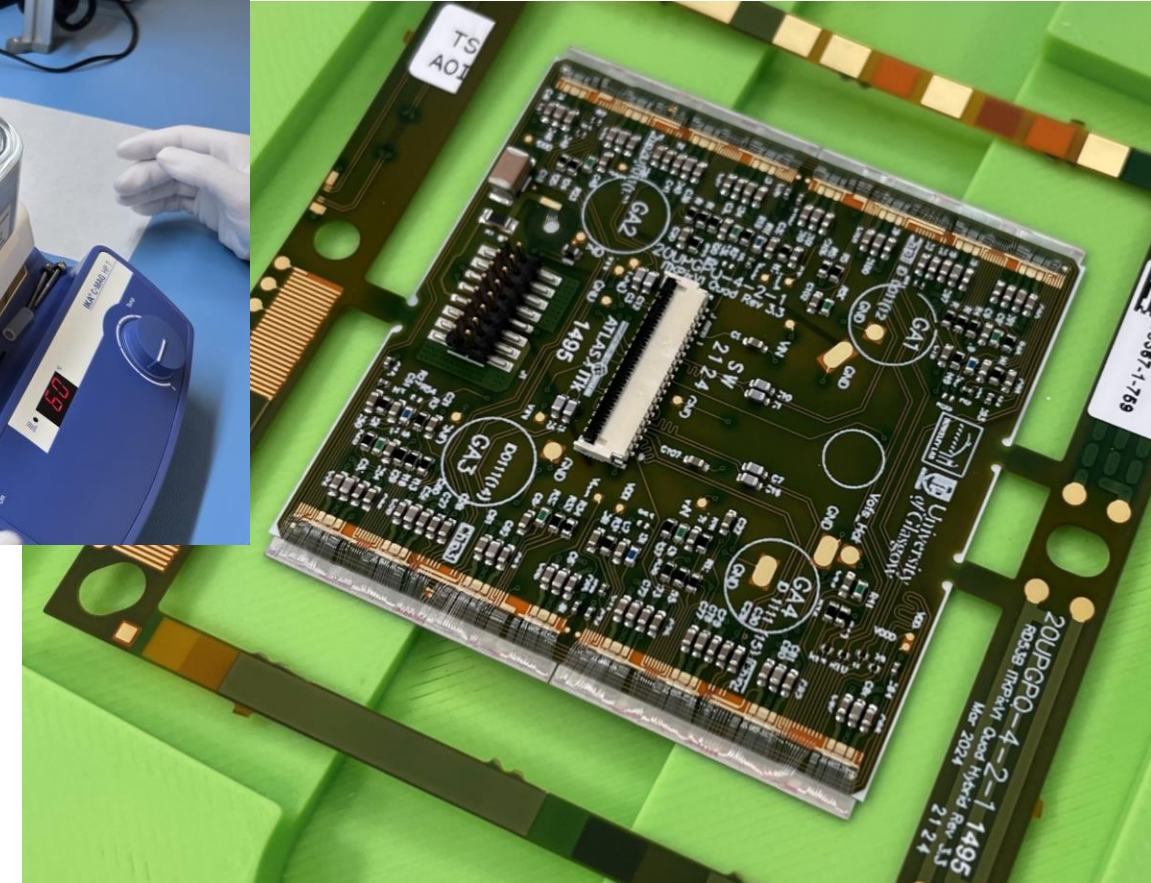


Assembly & Wirebonding

1. Glue flex to bare module
2. Metrology of module
3. Wirebonding
4. Pull tests

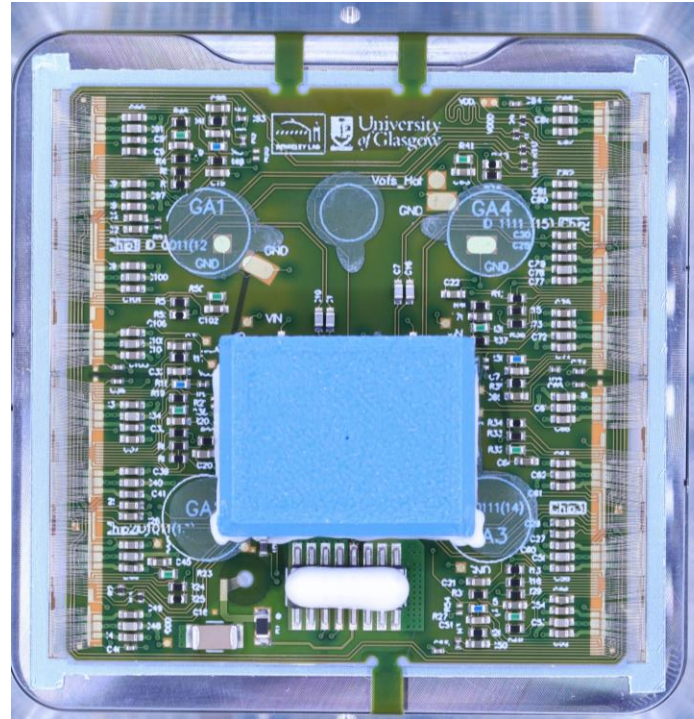
Assembly:
6 dedicated assembly tools

Wirebonding
2 wirebonding machines in operation
Pull tester for wirebonding QC



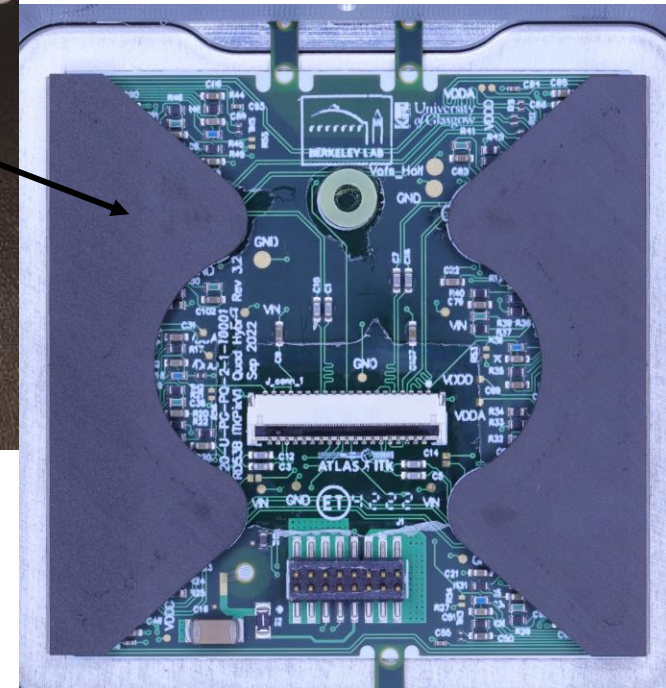
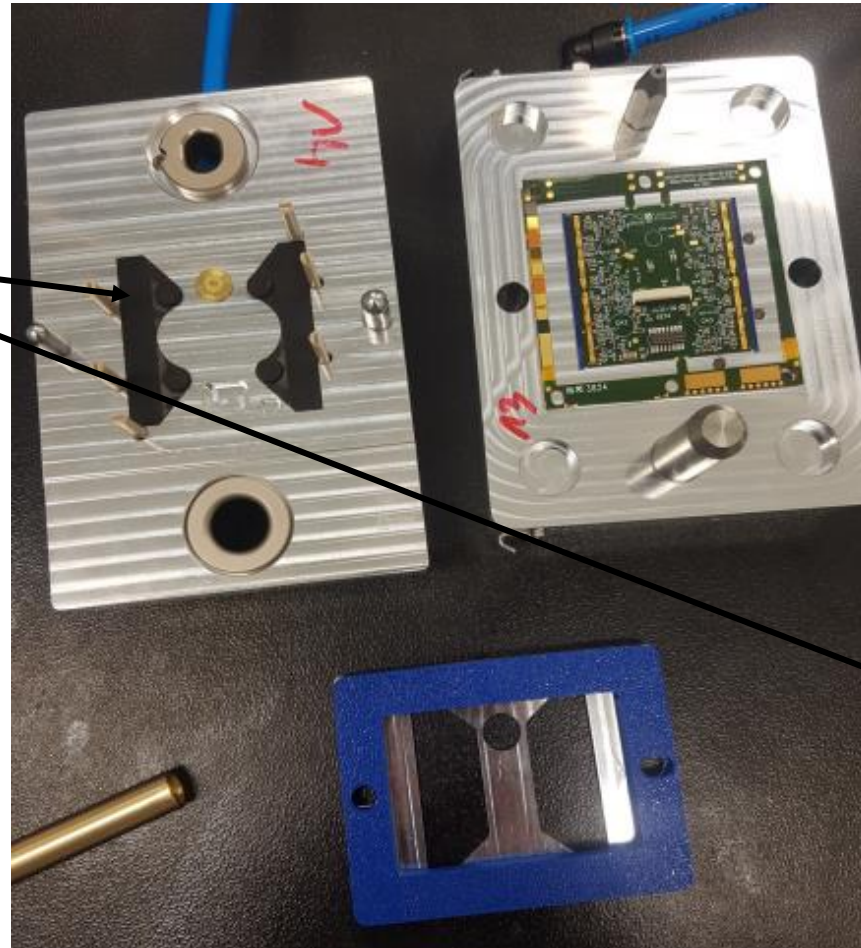
Parylene coating

1. Masking of module
2. Parylene coating (done externally)
3. De-masking of module



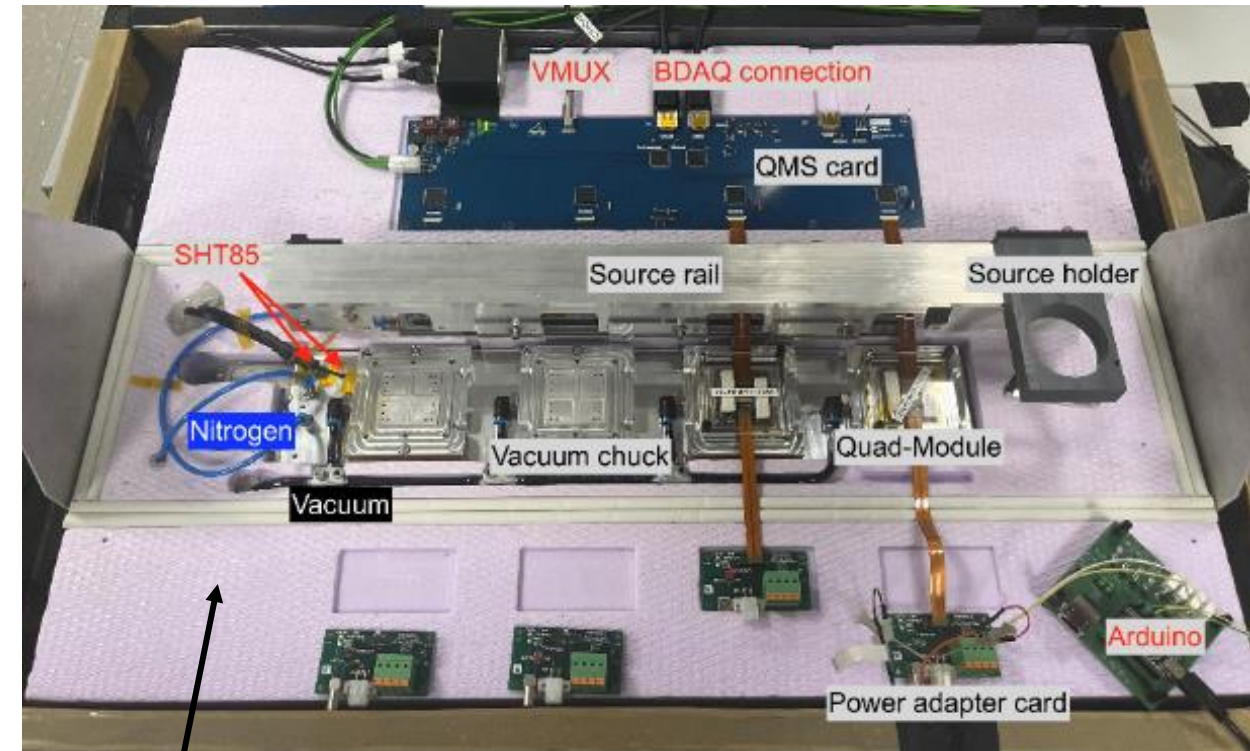
OBWBP (wirebond protection)

1. Attach wirebond protection
2. Final envelope measurement
3. Ready for final testing



Module Testing

- Dedicated test stand(s) for electrical testing
- Warm and cold testing
- Test stand features DCS and interlock system for unsupervised testing
- Done at various stages during module production
- Two test stands during production -> currently only one in operation (still in our lab)
- **Preparation for re-location of setup is ongoing**
 - One setup will move into ISO7 (in preparation)
 - One setup is planned for ISO6 -> used for tests with radioactive source
 - Instead of N2, we will use dried, pressured air using dedicated adsorption dryer (ATLAS Copco CD5) -> Jerome installed tubing for ISO6/7
- **Everything will be properly cleaned to keep cleanroom clean**



Styrodur is covered with tape to make the test setup compatible with clean room environment